ScanPUF: Robust Ultralow-Overhead PUF using Scan Chain

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Outline

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- Signature generation procedure
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- Discussion && Conclusion

The Fundamental of Physically Unclonable Function (PUF)

• Why PUF?

The storage of digital key in non-volatile memory is vulnerable to invasive attacks.

Highly tampering-resistance environment is expensive.

• What is PUF?

 Basically, a challenge-response protocol that exploits the inherent random variations in a manufacturing process to generate unique signatures.

The advantages of PUF

- Random and vast challenge-response pairs.
- Only available when the chip is running.
- Cost is lower than key storage of tampering-resistance.

Existing PUFs

Dedicated circuit structure

- Ring-oscillator PUF (RO-PUF)
- Arbiter PUF
- Butterfly PUF
- PE-PUF



Non-negligible area overhead.

- Utilization the on-chip structure
 - SRAM PUF
 - MECCA
 - Intrinsic PUF



Limited challengeresponse pairs or established on special structure.

Illustration of ScanPUF Realization

Signature generation cycle: 1 ns



The Architecture of ScanPUF



Signature Generation Illustration



Signature Generation Procedure

- Select the SFFs in a design to generate the signature.
- In the test mode, scan sequence of alternating '0' and '1' from primary inputs (PIs) into SFFs.
- Produce the signature-generation cycle.
- Shift out the response bits (signature) stored in the SFFs through primary outputs (POs).

Hspice Simulation Setup

- **128-bit signature** is evaluated in Hspice simulation under 45 nm PTM CMOS process.
- Process variation of V_{th} : $\sigma_{th,inter} = 15\%$ and $\sigma_{th0,intra} = 10\%$.
- Four inverters on each clock delay line of SGCC.
- Four inverters on each scan path.
- Eight clock delay lines are employed in the SGCC and each one produces an 16-bit signature.
- 1000 chips are simulated and 0 -> 1 is generated on the scan path.

Scan Path Distribution

Scan path follows the Gaussian distribution.



Median delay of each chip fluctuates largely due to the inter-die variation.

Signature Generation Cycle Controller (SGCC)

SGCC is comprised of N clock delay lines and a (N+1):1 multiplexor.



The switch between clock 1 and clock 2 generates a cycle of signature-generation period.

Architecture of SGCC



Timing of SGCC

Design keynote of SGCC for the signature of good uniqueness

Signature-generation cycle and scan path delay should have the approximate shift on the inter-die corner.



Approximate shift

The upsize of W and L drops the influence from the intra-die process variation.

Intra-die variation on SGCC

$$\sigma_{th,intra} = \sigma_{th0,intra} \cdot \sqrt{\frac{W_{min}L_{min}}{WL}}$$

minimum gate in a process

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Shannon Entropy Estimation

- The Shannon Entropy is related to: (1) selection of SFFs, (2) signature-generation cycles, (3) prestored value in SFF (0->1, 1->0 transition).
- For only one signature-generation cycle, the maximum entropy for one SFF under (0->1 or 1->0 transition) is one bit.
- For m signature-generation cycles, the maximum entropy for an SFF under (0->1 or 1->0 transition) is larger than one bit, but less than m bits.

Uniqueness analysis Signature-generation cycle (nominal) Equal Scan path delay (nominal)



Average Inter-die Hamming Distance (HD): 49.9% Probability of zero in the signature: 0.5 14



Probability of zero: 0.4

15

Probability of zero: 0.6

Robustness Analysis



18% bits flip when the supply voltage is reduced to 0.8 Volt from 1 Volt.

92.1% chips has no morethan 10 unstable bits within85 degree Celsius.

Aging Effect Analysis

Unstable-bit percentage under non-identical NBTI on clock delay line and scan paths.



For the identical shift on V_{th} , nearly 4% bits flip.

FPGA Validation

Structure of scan chain mapping into FPGA



Each basic structure is mapped into a LE for onebit signature with the delay as 5.42 ± 0.02 ns.

Totally, five 128-bit signatures are arranged on a FPGA from the top to bottom.

FPGA Validation (cont'd)

Result:



arge standard deviation of inter-die HD is due to the uncontrollability of intra-die V_{th} process variation on clock delay line because of the uniform structure of LE.¹⁹

Discussion

- Because of the unbalanced wire lengths, fanout loads and residual clock skewing, the nominal delays of different scan paths may be far ways from identity in real IC design.
- We can obtain the signature by two steps:
 - Put scan paths with near-identical nominal delays into a set.
 - Each set has a clock delay line to trigger its own signature bits and aggregate them from different sets as the signature.

Area Overhead

- We make the comparison on the area of 128-bit ScanPUF and RO-PUF.
- For the ScanPUF, 8 clock delay lines (four inverters each) are included in the signaturegeneration controller.
- For the RO-PUF, if all ordering of ROs are possible, it requires 35 2:1 MUXs, two 32-bit counters and one 32-bit comparators.

	RO-PUF	ScanPUF			
		w/ INVs	w/o INV	3	Vithout INVs
Area(um ²)	2721.40	303.96	62.04		on scan path
	e up to 6				21

Influence on Power

- Some inverters may be inserted into scan path that impacts the power of circuit in the function mode and test mode.
- For the function mode, power-gating can prevent the signal propagation on scan path and therefore incur no extra power overhead.
- For the test mode, when four inverters are on the scan path, the test power grows by 9.65% in Hspice.
- Since 78% test power is consumed by the combinational logic, taking 64-bit Alpha processor with 2408 SFFs for example, the overall power is increased by 0.11%.

Conclusion

- We have presented a novel PUF (ScanPUF) established on the scan chain, a prevalent on-chip structure.
- Since the on-chip structure is exploited, we show that the area overhead and design effort are reduced significantly.
- The extensive circuit-level Hspice simulation and FPGA validation show excellent signature uniqueness and robustness under temperature and supply voltage fluctuation and aging effect.
- It can provide a large number of challengeresponse pairs.

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Questions ??